



Datasheet

08x06SMDPt1000B-B

181001

Summary

This platinum-chip temperature sensor is characterized by its small size and can therefore allow a very high packing density. It is preferably used for automated assembly, for example, electrical printed circuit boards in large-scale production.

Dimensions in mm

	L	B	H	Solder-connection
	2,3 ±0,2	1,4 ± 0,2	0,6 ±0,2	Ca. 0,5

Technical specifications

Nominal resistance R_0 at 0°C	Specification	Tolerance	Order Number	Item Number
1000 Ω	DIN EN 60751	F 0,3 (DIN B)	08x06SMDPt1000B-B	181001

Temperature range:	-50 ° C to +150 ° C in continuous operation Validity of tolerance F 0.3: -50 ° C to +150 ° C		
Temperature coefficient:	TK = 3850 ppm / K		
Solder terminals:	SMD - V: tin plated with Ni barrier layer		
Operating conditions:	unprotected only in dry environments		
Insulation resistance:	> 10 MΩ at 20 ° C		
Measuring current:	0.1 mA to 0.3 mA (consider self-heating)		
Self-heating:	0.4 K / mW		
Response:	water current (v = 0.4 m / s):	$t_{0,5} = 0.10 \text{ s}$	$t_{0,9} = 0.25 \text{ s}$
	Air flow (v = 2 m / s):	$t_{0,5} = 2.5 \text{ s}$	$t_{0,9} = 8 \text{ s}$
Packaging:	Taped		
Note:	Please refer to our application and installation instructions.		
RoHS compliant			

Technische Änderungen behalten wir uns vor. Alle technischen Angaben sind Beschaffenheitsangaben und sichern keine Eigenschaften zu.

Version 1.0 vom 01/2007

